

GP1S50/GP1S51V
GP1S52V/GP1S54

General Purpose Photointerrupter

■ Features

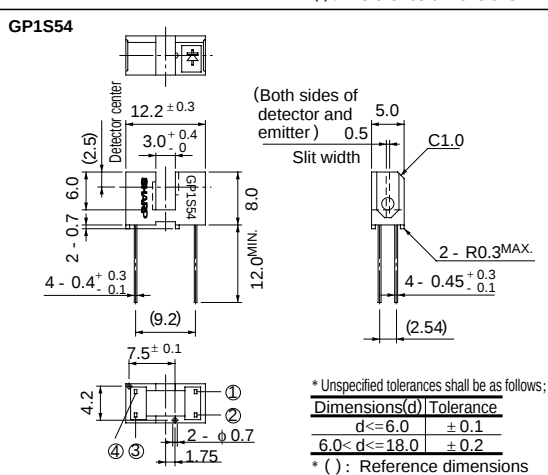
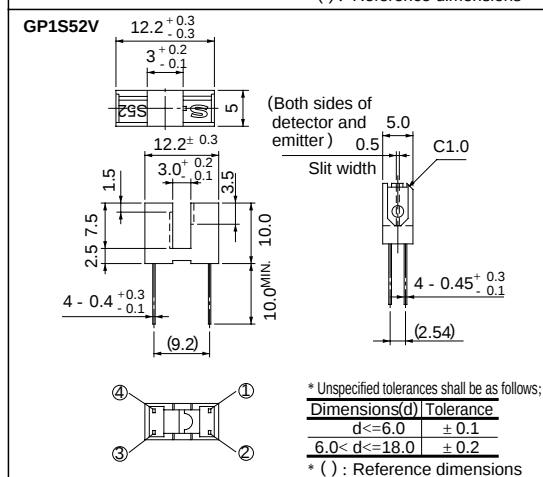
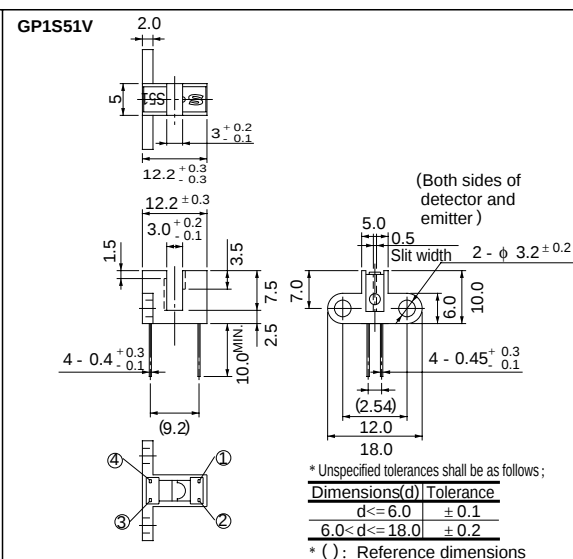
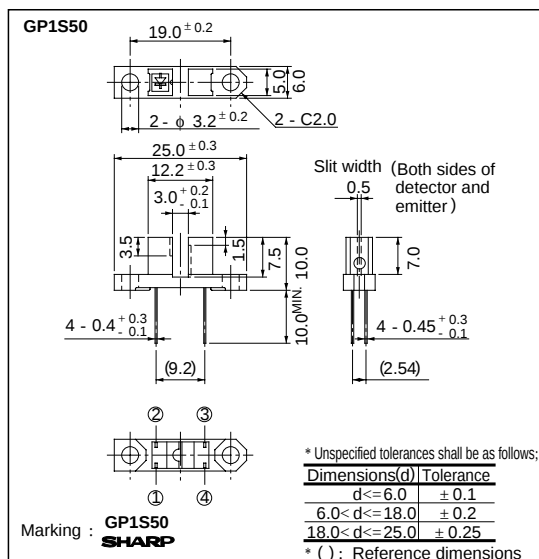
1. High sensing accuracy (Silt width : 0.5mm)
2. Both-sides mounting type : **GP1S50** (Case height : 10mm)
Either-side mounting type : **GP1S51V** (Case height : 10mm)
PWB direct mounting type : **GP1S52V** (Case height : 10mm)
PWB direct mounting type : **GP1S54** (Case height : 8mm)

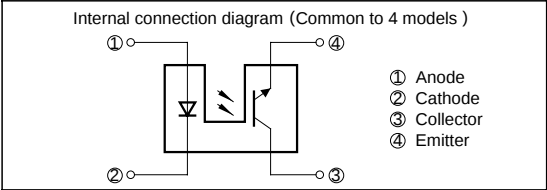
■ Applications

1. OA equipment, such as FDDs, printers, facsimiles
2. VCRs

■ Outline Dimensions

(Unit : mm)





■ Absolute Maximum Ratings

(Ta = 25°C)

Parameter		Symbol	Rating	Unit
Input	Forward current	I _F	50	mA
	*1Peak forward current	I _{FM}	1	A
	Reverse voltage	V _R	6	V
	Power dissipation	P	75	mW
Output	Collector-emitter voltage	V _{CEO}	35	V
	Emitter-collector voltage	V _{ECO}	6	V
	Collector current	I _C	20	mA
	Collector power dissipation	P _C	75	mW
Operating temperature		T _{opr}	- 25 to + 85	°C
Storage temperature		T _{stg}	- 40 to + 100	°C
*2 Soldering temperature		T _{sol}	260	°C

*1 Pulse width<=100μ s, Duty ratio= 0.01

*2 For 5 seconds

■ Electro-optical Characteristics

(Ta = 25°C)

Parameter			Symbol	Conditions	MIN.	TYP.	MAX.	Unit
Input	Forward voltage	GP1S50/ GP1S51V/ GP1S52V	V _F	I _F = 20mA	-	1.25	1.4	V
		GP1S54			-	1.2	1.4	
	Peak forward voltage		V _{FM}	I _{FM} = 0.5A	-	3	4	V
	Reverse current		I _R	V _R = 3V	-	-	10	μ A
Output	Collector dark current		I _{CEO}	V _{CE} = 20V	-	1	100	nA
Transfer characteristics	Collector Current		I _C	I _F = 20mA, V _{CE} = 5V	0.5	-	5	mA
	Collector-emitter saturation voltage		V _{CE (sat)}	I _F = 40mA, I _C = 0.5mA	-	-	0.4	V
	Response time	Rise time	t _R	V _{CE} = 2V, I _{CE} = 2mA R _L = 100 Ω	-	3	15	μ s
		Fall time	t _F		-	4	20	μ s

Fig. 1 Forward Current vs. Ambient Temperature

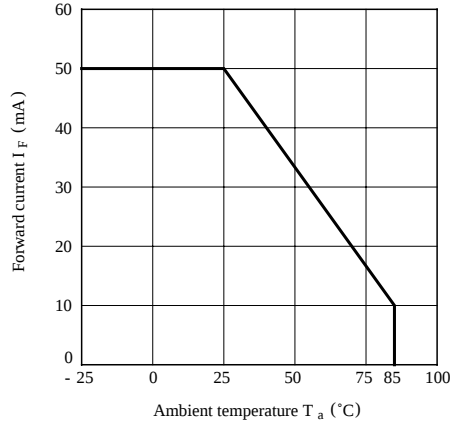


Fig. 2 Collector Power Dissipation vs. Ambient Temperature

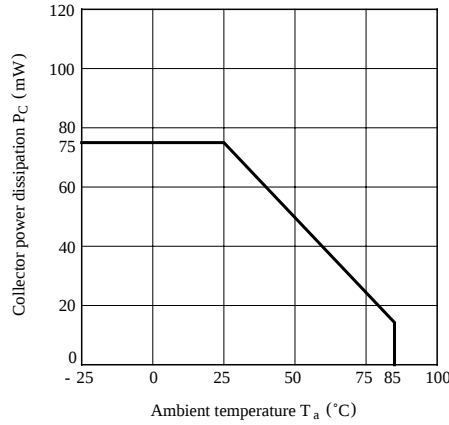


Fig. 3 Peak Forward Current vs. Duty Ratio

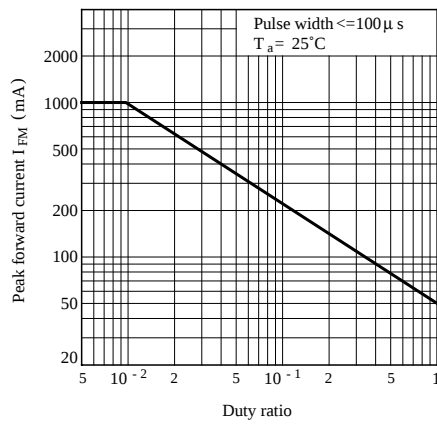


Fig. 4 Forward Current vs. Forward Voltage

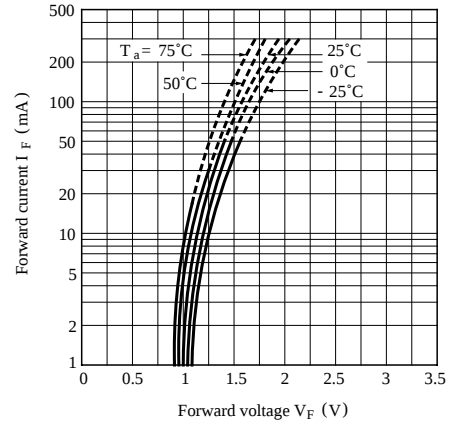


Fig. 5 Collector Current vs. Forward Current

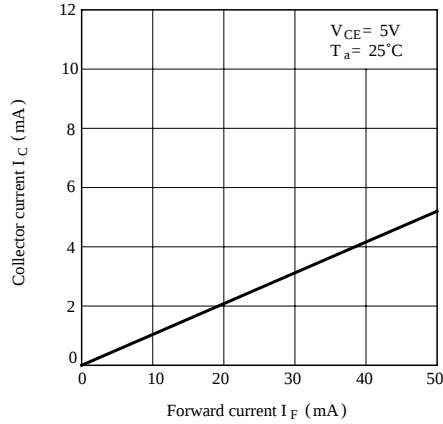


Fig. 6 Collector Current vs. Collector-emitter Voltage

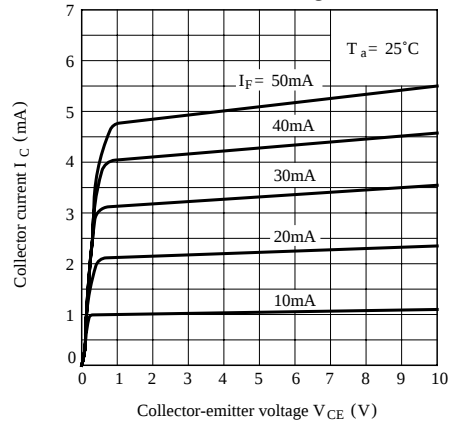


Fig. 7 Collector Current vs. Ambient Temperature

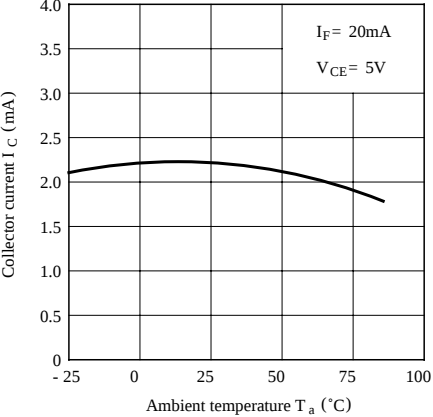


Fig. 8 Collector-emitter Saturation Voltage vs. Ambient Temperature

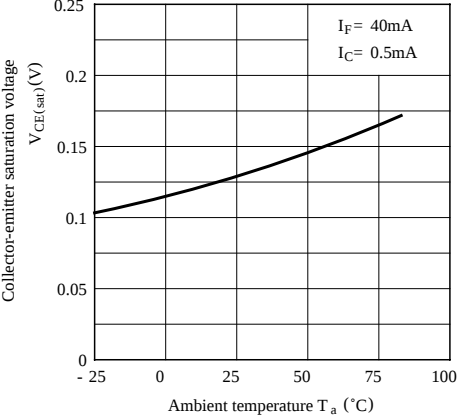
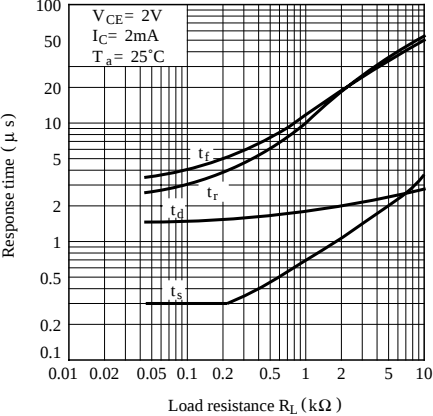


Fig. 9 Response Time vs. Load Resistance



Test Circuit for Response Time

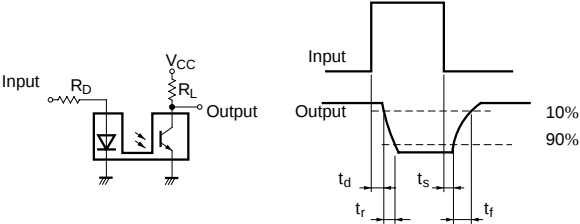


Fig.10 Frequency Response

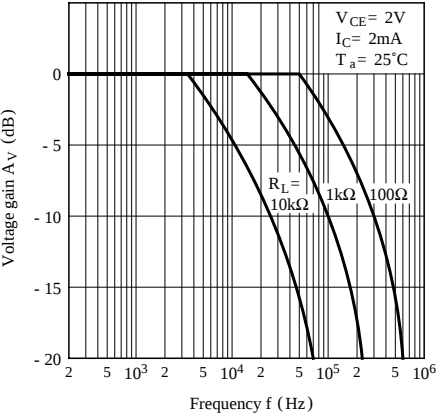


Fig.11 Collector Dark Current vs. Ambient Temperature

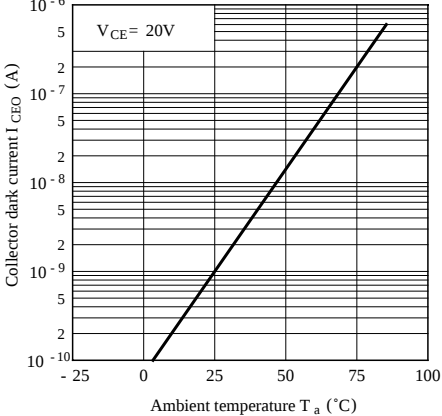


Fig.12 Relative Collector Current vs. Shield Distance (1)

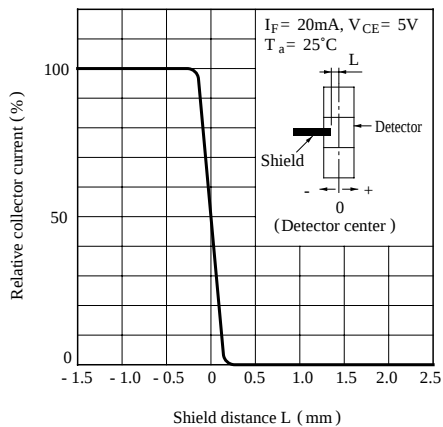
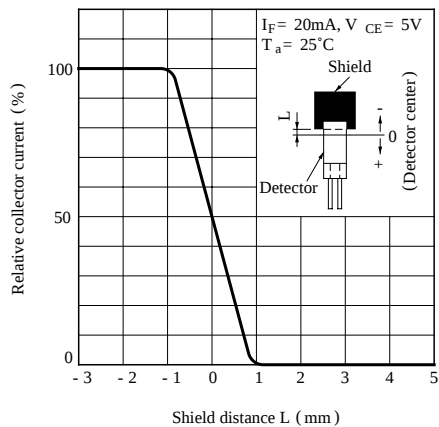


Fig.13 Relative Collector Current vs. Shield Distance (2)



■ Precautions for Use

- (1) In case of cleaning, use only the following type of cleaning solvent.
Ethyl alcohol, methyl alcohol, Isopropyl alcohol
- (2) Please refer to the chapter "Precautions for Use".

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